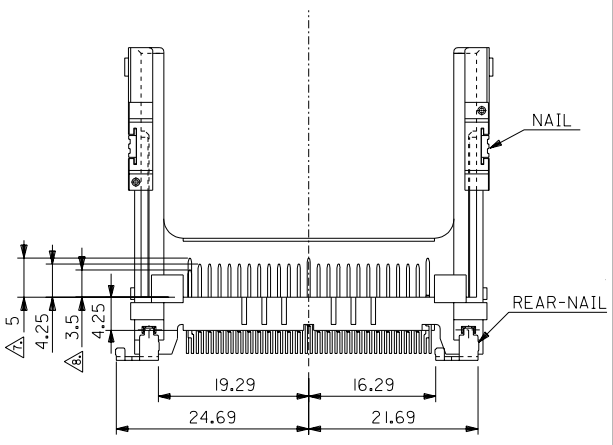
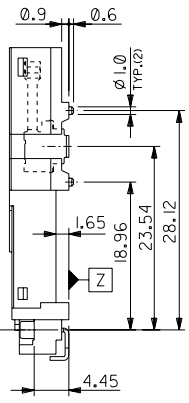
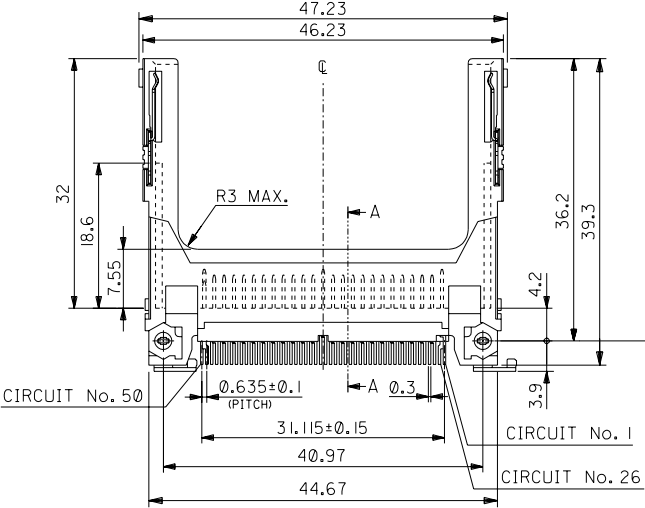
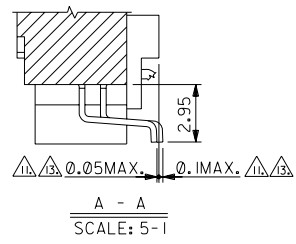
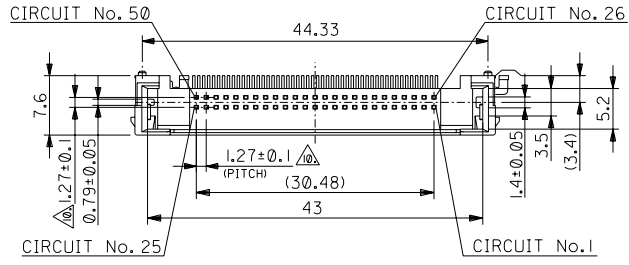


DWG. NO. SD-55358-014



DO NOT SCALE DRAWING

EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:

RELEASED
EC NO. J2004-3952
DRWN: MANABEI '04/04/22
CHK: K.TOJO '04/04/22
APPR: MASASAO '04/04/22

MATERIAL 材料	SEE NOTES
FINISH 仕上付	SEE NOTES
WIRE RANGE 適用電線範囲	—
INS. RANGE 被覆外径	—

GENERAL TOLERANCES: (UNLESS SPECIFIED) 一般公差	
10 UNDER 未満	+0.2
10 OVER 以上	+0.25
30 UNDER 未満	+0.25
30 OVER 以上	+0.3
ANGLE 角度	+3°

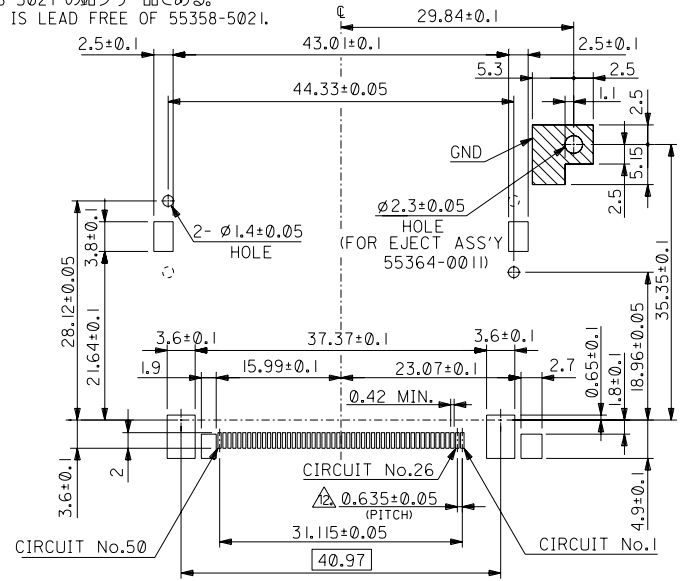
55358-5028	55358-5029	55358-50**
HARD TRAY PACKAGE	MATERIAL No.	MODEL No.
SCALE 2-1	DESIGN UNITS <input checked="" type="checkbox"/> mm <input type="checkbox"/> INCH	THIRD ANGLE PROJECTION
DRAWN BY & DATE M.NABEI '04/04/22	CHECKED BY & DATE K.TOJO '04/04/22	APPROVED BY & DATE H. Saito '04/04/22
TITLE: CF CARD CONN. 50P HEADER ASS'Y (TYPE I/II, NORMAL) -LEAD FREE-		MATERIAL NO. SD-55358-014
CAD FILENAME SD-55358-014.S01		DRAWING NO. SD-55358-014
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.		SHEET NO. 1 OF 2 SIZE B

EN-02J(097) MXJ-54

DWG. NO. SD-55358-014

- 注) 1. 材質 MATERIAL
 ハウジング: ガラス入りLCP UL94V-0
 HOUSING: LIQUID CRYSTAL POLYMER G.F. UL94V-0
 ピン: リン青銅
 PIN: PHOSPHOR BRONZE
 ネール: リン青銅 (t0.3)
 NAIL: PHOSPHOR BRONZE (t0.3)
 リヤネール: リン青銅 (t0.48)
 REAR-NAIL: PHOSPHOR BRONZE (t0.48)
2. メッキ仕様 PLATING
 ピン 接点部: パラジウムニッケル下地、金メッキ
 CONTACT AREA: GOLD OVER PALLADIUM-NICKEL
 半田付け部: 錫メッキ
 SOLDER TAIL AREA: TIN
 下地メッキ: ニッケルメッキ
 UNDERPLATING: NICKEL OVER ALL
 ネール 接点部: 金メッキ
 CONTACT AREA: GOLD
 半田付け部: 錫メッキ
 SOLDER TAIL AREA: TIN
 下地メッキ: ニッケルメッキ
 UNDERPLATING: NICKEL OVER ALL
 リヤネール 錫メッキ
 REAR-NAIL TIN
 下地メッキ: ニッケルメッキ
 UNDERPLATING: NICKEL OVER ALL
3. 推奨基板厚: t=0.8 MIN.
 RECOMMENDED P.C.B. THICKNESS: t=0.8 MIN.
4. 適合カード厚: 3.3±0.1 (TYPE I) AND 5 MAX. (TYPE II)
 RECOMMENDED CARD THICKNESS: 3.3±0.1 (TYPE I) AND 5 MAX. (TYPE II)
5. 適合カード幅: 42.8±0.1
 RECOMMENDED CARD WIDTH: 42.8±0.1
6. ハウジング色: 黒
 HOUSING COLOR: BLACK
- △ 寸法適用極: 1,13,38,50
 THIS DIMENSION APPLIES TO CIRCUIT NUMBERS 1,13,38 AND 50.
- △ 寸法適用極: 25,26
 THIS DIMENSION APPLIES TO CIRCUIT NUMBERS 25 AND 26.
- △ ピンの倒れは、ピン根元を基準に全方向へ0.1 MAX.とする。
 PIN TIP LEAN TOWARD ANY DIRECTION NOT TO EXCEED 0.1 WHEN MEASURED FROM PIN BASE.
- △ ピン根元に適用する。
 THIS DIMENSION TO BE MEASURED AT PIN BASE.

- △ ソルダータールは、Z面を基準とし上へ0.05下へ0.1の範囲にあり、目ツソルダータールの平坦度は、0.1 MAX.とし、テール先端にて測定する。
 SOLDER TAILS TO BE WITHIN 0.05 UPWARD AND 0.1 DOWNWARD FROM Z-DATUM PLACE, AND COPLANARITY OF SOLDER TAILS TO BE WITHIN 0.1. MEASUREMENT POINT IS SOLDER TAILS TIP.
- △ 公差非累積
 NON-CUMULATIVE
- △ テールとネール、リヤネールを併せた平坦度は、0.1 MAX.とする。
 TOTAL COPLANARITY OF SOLDER TAILS, NAILS AND REAR-NAILS TO BE 0.1 MAX.
14. 本製品は 55358-5021 の鉛フリー品である。
 THIS PRODUCT IS LEAD FREE OF 55358-5021.



基板推奨寸法
 RECOMMENDED P.C.B. LAYOUT

DO NOT SCALE DRAWING		REV APPR/SEE SHEET 1 OF 2		MATERIAL 材料 SEE NOTES		GENERAL TOLERANCES: (UNLESS SPECIFIED) 一般公差		SCALE 2-1 DESIGN UNITS mm INCH		MODEL NO. 55358-50**		DIMENSIONS: mm INCH mm ONLY		SHT REV REVISE ON CAD ONLY	
EC NO. DRWN: CHK: APPR:		EC NO. DRWN: CHK: APPR:		FINISH 仕上り SEE NOTES		10 UNDER 未満 +0.2		DRAWN BY & DATE M.NABEI '04/04/22		TITLE: CF CARD CONN. 50P HEADER ASS'Y (TYPE I/II, NORMAL) -LEAD FREE-		MATERIAL NO. SD-55358-014		SHEET NO. 2	
EC NO. DRWN: CHK: APPR:		EC NO. DRWN: CHK: APPR:		WIRE RANGE 適用電線範囲		10 OVER 30 UNDER 未満 +0.25		CHECKED BY & DATE K.TOJO '04/04/22		MOLEX INCORPORATED		DRAWING NO. SD-55358-014		SIZE B	
EC NO. DRWN: CHK: APPR:		EC NO. DRWN: CHK: APPR:		INS. RANGE 被覆外径		30 OVER 以上 +0.3		APPROVED BY & DATE H. SAKAI '04/04/22		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.		EN-02J(097) MJJ-54			
		0				ANGLE 角度 +3°		CAD FILENAME SD-55358-014.S02							